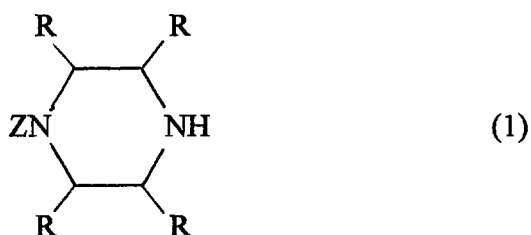


ABSTRACT

An IC card which comprises an IC substrate, a hot-melt resin layer, and a skin material and in which these three layers are tenaciously bonded to each other and are less apt to peel off. The IC card is capable of deep embossing. Problem has been solved by employing a resin composition comprising the following specific polyester and a polyamide, as a hot-melt resin:

Polyester: saturated copolyester having cyclohexanedimethanol units as polyol units,

Polyamide: copolyamide having units derived from a compound represented by the following general formula (1) as polyamine units



(wherein each R is a hydrogen atom or an alkyl group having 1-4 carbon atoms, provided that the four Rs may be the same or different; and Z is a hydrogen atom or an $\text{NH}_2\text{R}'$ group, wherein R' is an alkylene group having 1-4 carbon atoms).



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